

REMARKS

Claims 1-12 and 38-40 will be pending upon entry of the present amendment. Claims 38-40 have been allowed by the Examiner.

Applicant thanks the Examiner for consenting to a phone interview with the undersigned representative on November 19, 2003. In that interview, it was pointed out to the Examiner that the issuance of an Ex parte Quayle action at this time is inappropriate, inasmuch as the Examiner has not indicated that all the claims in the application are allowed, as required under MPEP 714.14. In a previous response to a Restriction Requirement, the applicant elected Species III (Figure 11) and listed claims 1-4, 6, 8-12, 30-31, and 34-40 as reading on the elected species, including generic claims 1-4, 6, 9-12, 31, and 34-36. Nevertheless, the Examiner withdrew all claims, save 38-40, from further consideration, as being drawn to a nonelected invention.

During the interview, the undersigned reviewed the limitations of claim 1 with the Examiner, demonstrating that at least claim 1 reads on the elected species. The Examiner acknowledged this, and indicated a willingness to reopen examination following an appropriate response by the applicant. The current document constitutes said response.

The applicant wishes to reiterate that many of the claims are generic to all species. In particular, independent claims 1, 30, 34, 35, and 36 are generic. For example, while claim 1 is not limited to the embodiments illustrated in the figures, claim 1 reads on the species of Figures 4 and 10-12, as described hereafter.

Claim 1 recites: forming integrated structures including semiconductor regions (10 and 15 of Figure 4, and 58 and 59 of Figures 10-12) and isolation regions (7 of Figure 4 and 55 of Figures 10-12) in a first wafer (1, 51, 81, and 101, respectively) of semiconductor material; forming interconnection structures of conductor material on a second wafer (25, 52, 82 and 102, respectively) of semiconductor material, including forming plug elements (32 of Figure 4, and 68 of Figures 10-12), each including a base region (33, 69) and a bonding region (34, 70), the bonding region of a metal material different from the base region and capable of reacting with said semiconductor regions of said first wafer; and bonding said first wafer and said second

wafer together, including causing said bonding regions (34, 70) to react with said semiconductor regions (10 and 15, 58 and 59).

If the Examiner would like a similar analysis of the other generic claims, applicant urges the Examiner to contact the undersigned, who will gladly oblige.

Upon finding a generic claim allowable, applicant requests consideration of those claims directed to nonelected species (claims 5, 7, 32, and 33), as permitted under 37 CFR 1.141(a).

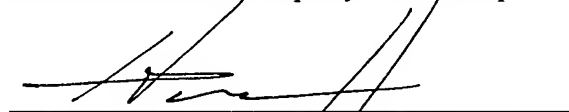
Claim 30 has been amended to improve readability. This amendment was not made for reasons of patentability and does not affect the scope of the claim.

All of the claims remaining in the application are now clearly allowable. Favorable consideration and a Notice of Allowance are earnestly solicited. In the event the Examiner finds minor informalities that can be resolved by telephone conference, the Examiner is urged to contact applicants' undersigned representative at (206) 622-4900 in order to expeditiously resolve prosecution of this application.

The Director is authorized to charge any additional fees due by way of this Amendment, or credit any overpayment, to our Deposit Account No. 19-1090.

Respectfully submitted,

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